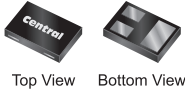
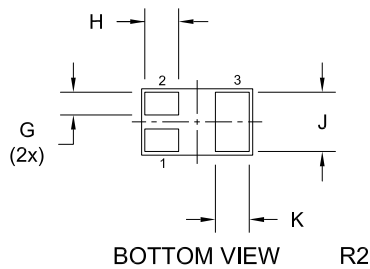
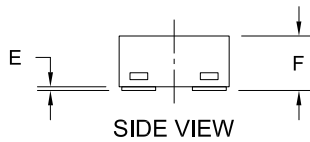
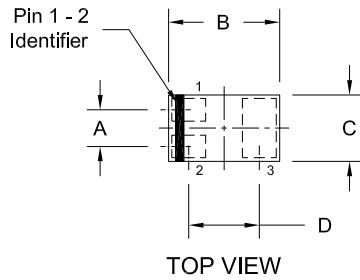


# Package Details

## SOT-883L Case



### Mechanical Drawing



DIMENSIONS				
SYMBOL	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.014		0.35	
B	0.037	0.041	0.95	1.05
C	0.022	0.026	0.55	0.65
D	0.026		0.65	
E	0.000	0.002	0.00	0.05
F	0.012	0.016	0.30	0.40
G	0.005	0.007	0.13	0.18
H	0.008	0.012	0.20	0.30
J	0.018	0.022	0.45	0.55
K	0.008	0.012	0.20	0.30

SOT-883L (REV:R2)

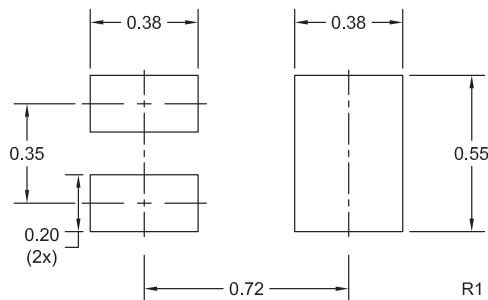
#### Part Marking:

Single Character Alpha/Numeric Code

#### Lead Code:

Reference individual device data sheet.

### Mounting Pad Geometry (Dimensions in mm)



R2 (7-February 2013)

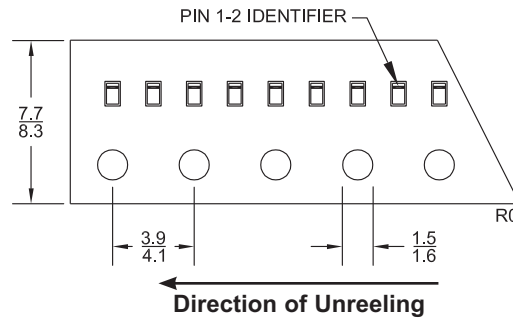
# Package Details

## SOT-883L Case



### Tape Dimensions and Orientation (Dimensions in mm)

Tape Width: 8mm



Devices are taped in accordance with Electronic Industries Association Standard EIA-481-D

### Packaging Base

7" Reel = 8,000 pcs.

### Reel Labeling Information

Each reel is labeled with the following information:

Central Part Number, Customer Part Number, Purchase Order Number, Quantity, Lot Number, Date Code, Ship Date and Marking Code.

### Reel Packing Information

Reel Size	Reels per Box (Maximum)	Parts per Box (Maximum)	Box Dimensions		Shipping Weight (Max.)	
			INCH	CM	LB	KG
7"	9	72,000	9x9x5	23x23x13	3	2
	18	144,000	9x9x9	23x23x23	6	3
	40	320,000	21x9x9	53x23x23	13	6
	108	864,000	27x9x17	69x23x43	34	16

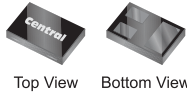
### Ordering Information

- For devices taped and reeled on 7" reels, add TR suffix to part number.
- All SMDs are available in small quantities for prototype and manual placement applications.

R2 (7-February 2013)

# Material Composition Specification

## SOT-883L Case



Device average mass . . . . . **0.75 mg**  
 Fluctuation margin . . . . . **+/-10%**

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	2.67%	0.02	Si	7440-21-3	2.67%	0.02	26,667
bond wire	gold	0.8%	0.006	Au	7440-57-5	0.8%	0.006	8,000
leadframe	copper	44.63%	0.335	Cu	7440-50-8	44.63%	0.3347	446,267
die attach	silver epoxy	2.73%	0.021	Ag	7440-22-4	1.93%	0.0145	19,333
				epoxy resin	Proprietary	0.8%	0.006	8,000
encapsulation*	EMC GREEN	47.41%	0.356	silica (fused)	60676-86-0	40.53%	0.304	405,333
				epoxy resin	29690-82-2	3.8%	0.0285	38,000
				phenol resin	9003-35-4	1.89%	0.0142	18,933
				carbon black	1333-86-4	0.24%	0.0018	2,400
				metal hydroxide	1309-42-8	0.95%	0.0071	9,467
plating	Ni/Pd/Au	1.76%	0.013	Ni	7440-02-0	1.69%	0.0127	16,933
				Pd	7440-05-3	0.05%	0.0004	533
				Au	7440-57-5	0.01%	0.0001	133
	matte tin		1.76%	0.013	Sn	7440-31-5	1.76%	0.013

\*EMC GREEN molding compound is Halogen-Free.

**Disclaimer**

The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.

R2 (3-June 2011)